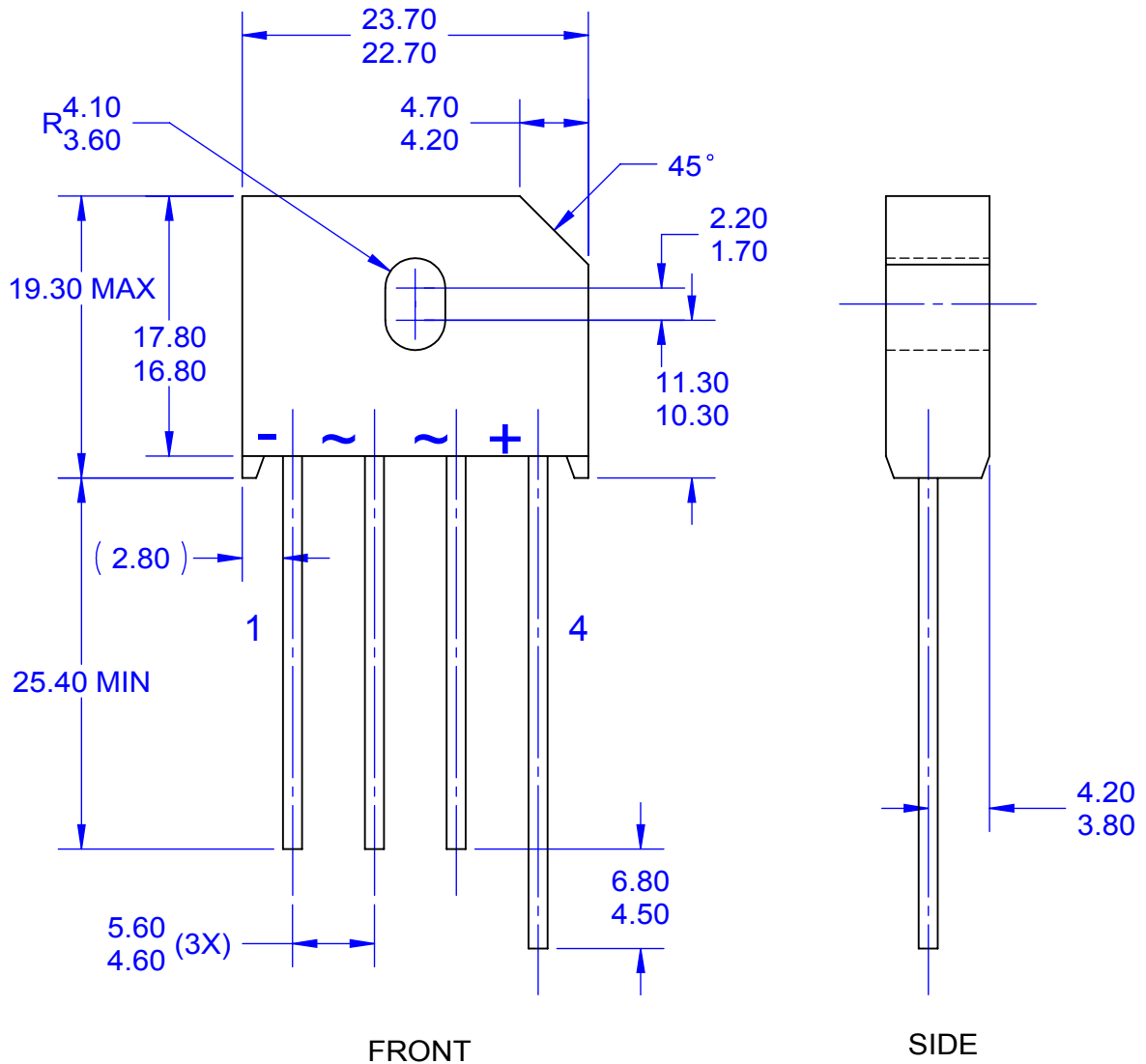


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REVISIONS

NBR	DESCRIPTION	DATE	BY/APP'D
1	RELEASED TO DCC	20APR09	G.CHEW/ SUZHOU



NOTES:

- A. THIS PACKAGE DOES NOT CONFORM TO ANY STANDARD.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- D. DRAWING FILE NAME: KBU04AREV1

APPROVALS		DATE	FAIRCHILD SEMICONDUCTOR™		
DRAWN: BOBOY MALDO		20APR09	4LD, KBU, THROUGH-HOLE, MOLDED PACKAGE		
CHECKED: BENJO ROLUNA					
APPROVED: G. CHEW					
APPROVED: HOWARD ALLEN					
PROJECTION			SCALE 1:1	SIZE N/A	DRAWING NUMBER MKT-KBU04A
					REV 1
			FORMERLY: N/A	SHEET: 1 OF 1	